
AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A system for cooling coated semiconductor substrates, said system comprising:
- a chamber ~~adapted to receive~~ for receiving at least one coated semiconductor substrate;
 - a coupling coupled to the chamber and a fluid reservoir for placing the chamber in fluid communication with a the fluid reservoir;
 - an inlet valve attached to the coupling for controlling a flow of cooling fluid between the fluid reservoir and the chamber, wherein the pressure drop across the inlet valve is at least about 10 bar; and
 - a controller coupled to the inlet valve for controlling the inlet valve.
2. (Cancelled)
3. (Original) The system of claim 2 wherein the pressure drop across the inlet valve is at least about 100 bar.
4. (Currently Amended) The system of claim 1 wherein the controller controls the temperature of the cooling fluid at a point within the chamber.
5. (Currently Amended) The system of claim 1 further comprising an outlet valve for controlling ~~the~~ a flow of cooling fluid out of the chamber, wherein the controller also controls the outlet valve.

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6. (Currently Amended) The system of claim 5 wherein the controller controls the rate of cooling fluid flow through the chamber.

7. (Currently Amended) The system of claim 1 wherein ~~the~~ cooling fluid entering the chamber from the reservoir substantially mixes with fluid already in the chamber before contacting the ~~substrates~~ at least one semiconductor substrate.

8. (Currently Amended) The system of claim 7 further comprising a baffle, wherein the cooling fluid flowing into the chamber is directed against the baffle.

9-20. (Withdrawn)

21. (Cancelled)